

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC039N06NS	**Issued**	9. January 2019
MA#	MA004297404		
Package	PG-TDSON-8-45	**Weight***	118.24 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	0.53	0.53	5321	5321
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		320	
	non noble metal	copper	7440-50-8	37.762	31.93	31.97	319366	319782
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	384	384
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		737	
	plastics	epoxy resin	-	6.880	5.82		58187	
	inorganic material	silicondioxide	60676-86-0	36.577	30.94	36.83	309350	368274
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12277	12277
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1400	1400
solder	non noble metal	tin	7440-31-5	0.019	0.02		158	
	noble metal	silver	7440-22-4	0.023	0.02		198	
	non noble metal	lead	7439-92-1	0.895	0.76	0.80	7566	7922
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.57	9.58	95739	95864
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
	non noble metal	copper	7440-50-8	22.292	18.85	18.88	188530	188776
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com